

Foamed Polyurethane Pad

IC1000™

Our IC1000™ CMP pad can achieve good performance balance of stability, reliability and polishing performance. IC1000™ has been qualified for a lot of CMP processes that need the highest requirement in industry and still maintain high market share.

Because our pads are designed with unique and special materials, processing and application/evaluation skills, they can deliver an excellent performance to our customers.

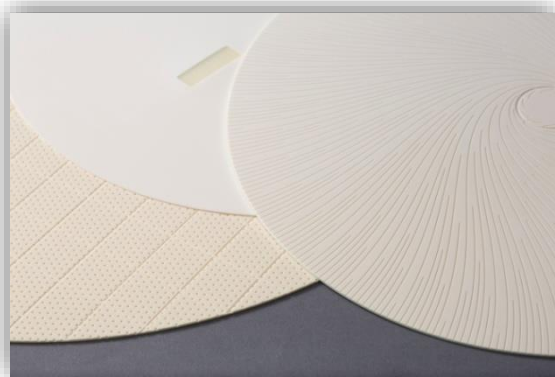
IC1000™ Series

IC1000™ is the de-facto standard as CMP pad. This product has an unique structure which has very small and uniform pores based on a special polyurethane material. It can achieve better slurry retention ability and high polishing removal rate with appropriate pad surface groove that helps slurry to spread quickly to under the wafer.

Physical Properties

	Spec Range (※)
Thickness (mm)	1.17 – 1.37
Compressibility (%)	0.5 – 4.0
Hardness (Shore-D)	52 – 62
Specific Gravity (g/cm ³)	0.77 – 0.83

(※) The specification of Type A6

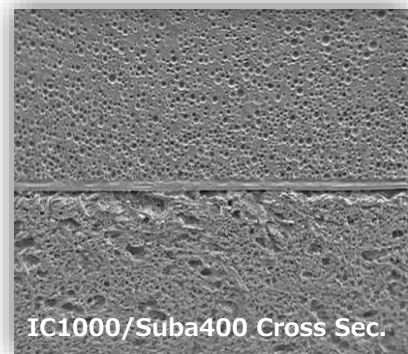


Grooving

- Perforation
- XY groove
- Circulation groove
- Combination groove
- Spiral groove

Stacked Pad

- Stacked pad with Suba™ series can achieve good removal rate uniformity.



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※ The values such as a physical properties indicated, show the standard value. The product specifications are not guaranteed.